Specifications for Approval

Customer Part No.:

Inhere Part No.: S1608BHMGBT-001

Part Name: 1608 绿蓝双色 LED

Spec Issue Date: 2018-09-18

Revision No.: A

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To Customer:

We submit herewith the following information for your approval:

■Sample ☐OQC Inspection Record ■LED Dimension

■Electrical Characteristics Curve ■Internal Circuit Diagram

■Soldering recommendation

Prepared by: Lily	Checked by: Tom	Approved by: Wangxiaojun
Date: 2018-09-18	Date: 2018-09-18	Date: 2018-09-18

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Customer Opinion

☐ Approve and no objection

☐ Reject with the following reason:

_____

inhere light for your mind 银河光电

东莞市银河光电有限公司
DongGuan Inhere Opto CO.,LTD.
地址:东莞市莞城科技园 D 幢
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TEL: 0769-23320868 FAX: 0769-23320878
E-mail: bill@inhereopto.com
Http://www.inhereopto.com

Features

1.6mm x 0.8mm SMD LED, 0.6mm thickness

Low power consumption

Wide view angle

Package: 4000pcs/reel

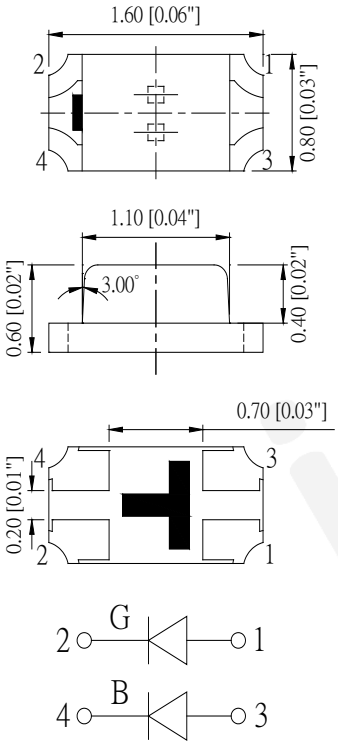
RoHS Compliant

Applications

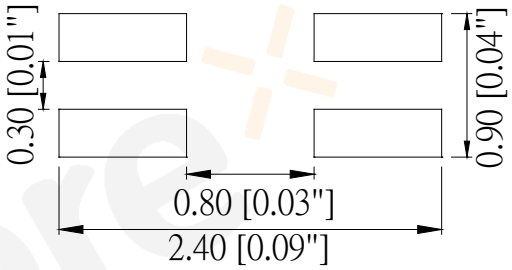
Ideal for back light and indicator

Various colors and lens types available

Package outlines



Recommend Pad Layout



Part No.	Emitted color	Dice	Lens color
S1608BHMGBT-001	Green	InGaN/GaN	Water transparent
	Blue	InGaN/GaN	

Notes:

1. All dimensions are in millimeters (inches);
2. Tolerances are ±0.1mm (0.004inch) unless otherwise noted.

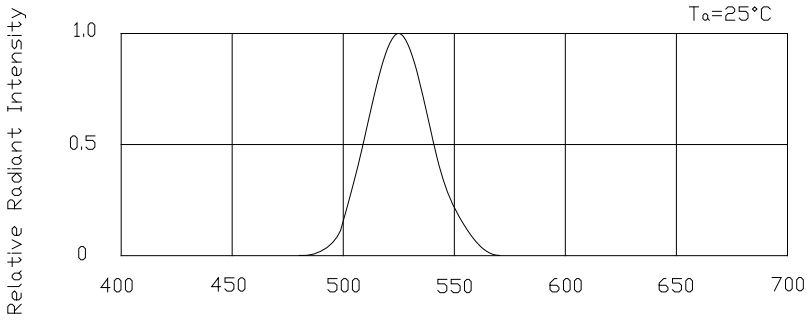
Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Value		Unit
		G	B	
Power dissipation	Pd	111	111	mW
Forward current	If	30		mA
Reverse voltage	Vr	5		V
Operating temperature	Top	-40 ~+80		℃
Storage temperature	Tstg	-40 ~+85		℃
Peak pulsing current (1/8 duty f=1kHz)	Ifp	125		mA

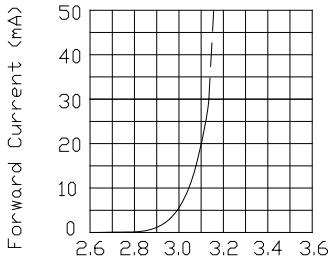
Electro-Optical Characteristics (Ta=25℃)

Parameter	Test Condition	Symbol		Value			Unit
				Min	Typ	Max	
Wavelength at peak emission	If=20mA	λp	G	--	520	--	nm
			B	--	465	--	
Spectral half bandwidth	If=20mA	△λ	G	--	35	--	nm
			B	--	25	--	
Dominant wavelength	If=20mA	λd	G	520	--	530	nm
			B	465	--	475	
Forward voltage	If=20mA	Vf	G	2.8	--	3.7	V
			B	2.8	--	3.7	
Luminous intensity	If=20mA	Iv	G	320	500	--	mcd
			B	100	150	--	
Viewing angle at 50% Iv	If=10mA	2θ1/2		--	120	--	Deg
Reverse current	Vr=5V	Ir		--	--	10	μA

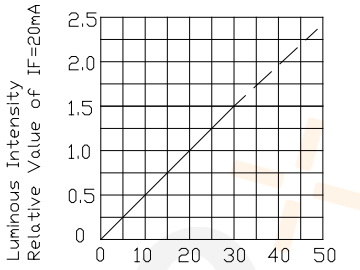
Optical Characteristic Curves (Green)



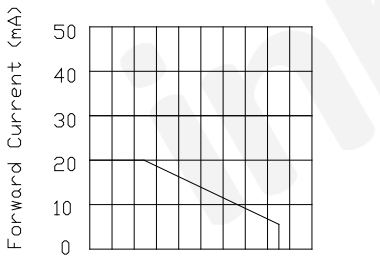
RELATIVE INTENSITY Vs.WAVELENGTH



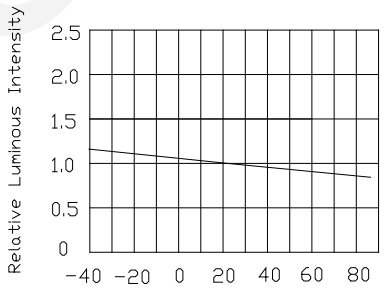
FORWARD CURRENT Vs.
FORWARD VOLTAGE



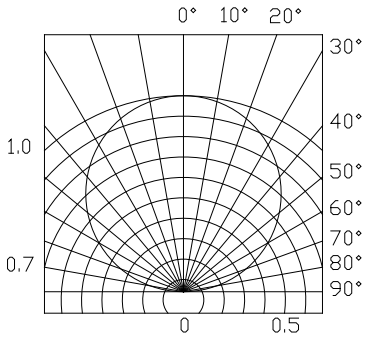
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



FORWARD CURRENT
DERATING CURE

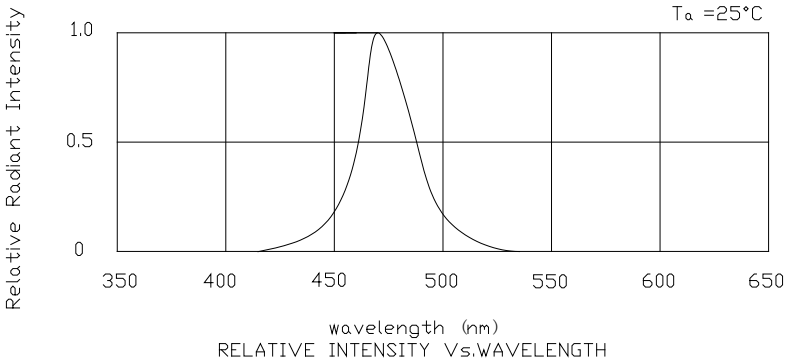


LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

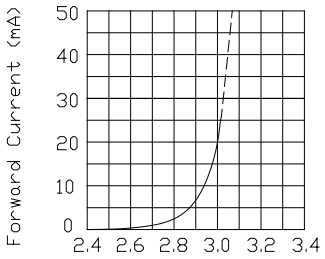


SPATIAL DISTRIBUTION

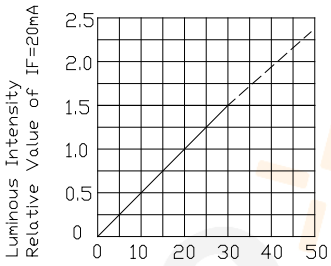
Optical Characteristic Curves (Blue)



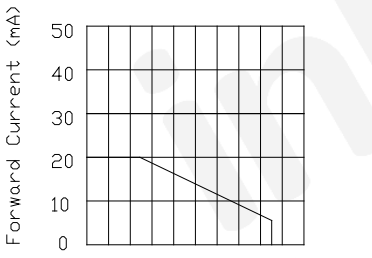
RELATIVE INTENSITY Vs.WAVELENGTH



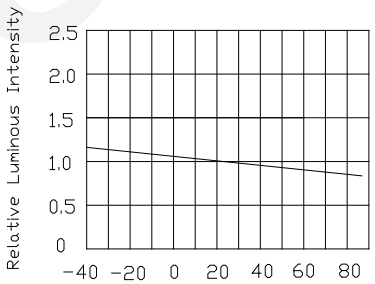
FORWARD CURRENT Vs.
FORWARD VOLTAGE



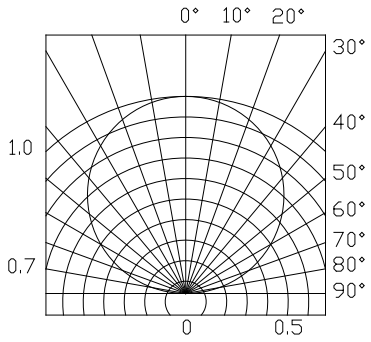
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



FORWARD CURRENT
DERATING CURE



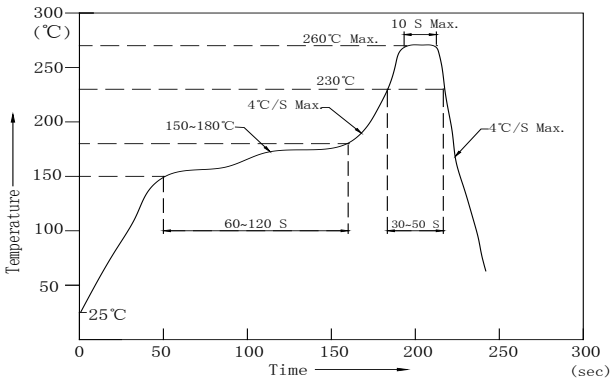
LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE



SPATIAL DISTRIBUTION

Reflow Profile

■ Reflow Temp/Time



Notes:

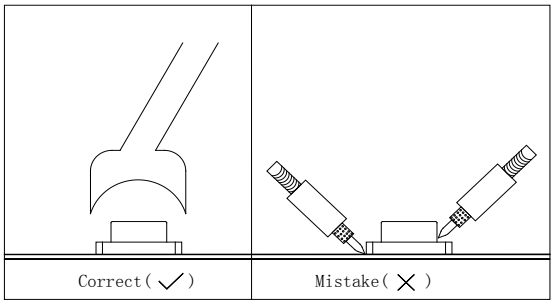
1. We recommend the reflow temperature 245℃ (±5℃).the maximum soldering temperature should be limited to 260℃.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

■Soldering iron

Basic spec is ≤ 5sec when 320℃ (±20℃). If temperature is higher, time should be shorter (+10℃→ -1sec). Power dissipation of iron should be smaller than 20W, and temperatures should be controllable .Surface temperature of the device should be under 350℃.

■Rework

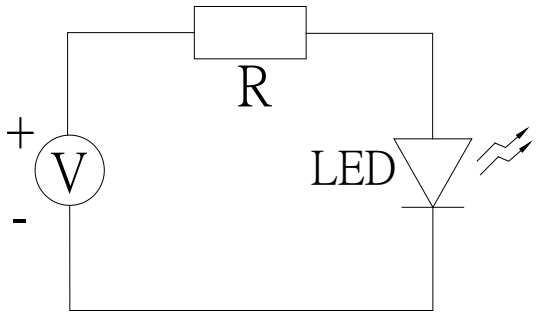
1. Customer must finish rework within 5 sec under 340℃.
2. The head of iron cannot touch copper foil
3. Twin-head type is preferred.



■ Avoid rubbing or scraping the resin by any object, during high temperature, for example reflow solder etc.

Test circuit and handling precautions

■ Test circuit



■ Handling precautions

1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 It is recommended to store the products in the following conditions:

Humidity: 60% R.H. Max.

Temperature: 5℃~30℃

2.2 Shelf life in sealed bag: 12 month at ＜5℃~30℃ and ＜30% R.H. after the package is opened, the products should be used within a week or they should be keeping to stored at≦20 R.H. with zip-lock sealed.

3. Baking

It is recommended to baking before soldering when the pack is unsealed after 72hrs. The Conditions are as followings:

3.1 60±3℃ x(12~24hrs) and ＜5%RH, taped reel type

3.2 100±3℃ x (45min~1hr), bulk type

3.3 130±3℃ x (15~30min), bulk type

Test Items and Results of Reliability

Test Item	Test Conditions	Standard Test Method	Note	Number of Test
Reflow Soldering	Ta=260±5℃,Time=10±2S	JB/T 10845-2008	3times	0/22
Salt Atmosphere	Ta=35±3℃,PH=6.5～7.2	GB/T 2423.17-2008	24hrs	0/22
Temperature Cycling	-40±5℃ 30±1min ↑→(25℃/5±1min)↓ 100±5℃ 30±1min	GB/T 2423.22-2012	100cycles	0/22
Thermal Shock	Ta=-40±5℃～100±5℃, 15±1min dwell	GB/T 2423.22-2012	100cycles	0/22
High Humidity High Temp. Cycling	Ta=30±5℃～65±5℃, 90±5%RH,24hrs/1cycle	GB/T 2423.4-2008	10cycles	0/22
High Humidity High Temp. Storage Life	Ta=85±5℃,ψ(%)=85±5%RH	GB/T 2423.3-2006	1000hrs	0/22
High Temperature Storage Life	Ta=100±5℃,non-operating	GB/T 2423.2-2008	1000hrs	0/22
Low Temperature Storage Life	Ta=-40±5℃,non-operating	GB/T 2423.1-2008	1000hrs	0/22
Life Test	Ta=26±5℃,@20mA, ψ(%)=25%RH～55%RH	--	1000hrs	0/22
High Humidity High Temp. Operating Life	Ta=85±5℃,@20mA, ψ(%)=85%RH	GB/T 2423.3-2006	500hrs	0/22
Low Temperature Operating Life	Ta=-20±5℃,@20mA	GB/T 2423.1-2008	1000hrs	0/22

Forward Voltage Rank Combination (IF=20mA)

Rank		Min.	Max.	Unit
Green	f	2.8	3.1	V
	g	3.1	3.4	
	h	3.4	3.7	
Blue	f	2.8	3.1	
	g	3.1	3.4	
	h	3.4	3.7	

Luminous Intensity Rank Combination (IF=20mA)

Rank		Min.	Max.	Unit
Green	O	320	400	mcd
	P	400	500	
	Q	500	630	
	R	630	800	
	S	800	--	
Blue	J	100	125	
	K	125	160	
	L	160	200	
	M	200	250	
	N	250	--	

Dominant wavelength Rank Combination (IF=20mA)

Rank		Min.	Max.	Unit
Green	U	520	522.5	nm
	V	522.5	525	
	W	525	527.5	
	X	527.5	530	
Blue	G	465	467.5	
	H	467.5	470	
	I	470	472.5	
	J	472.5	475	

Group Name on Label (Example DATA: gPU gHF 20)

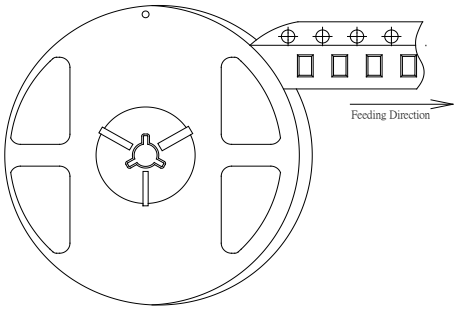
DATA: gPU gHF 20		Vf(V)	Iv (mcd)	λd (nm)	Test Condition
Green	g→P→U→20	3.1~3.4	400~500	520~522.5	IF=20mA
Blue	g→H→F→20	3.1~3.4	125~160	467.5~470	

Notes:

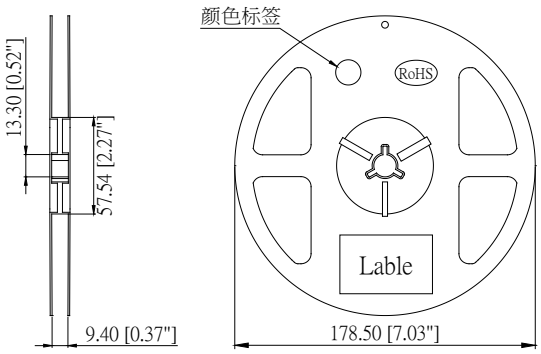
1. The tolerance of luminous intensity (Iv)is ±15％.
2. The tolerance of dominant wavelength is ±1nm.
3. This specification is preliminary.
4. This specification is a standard specification of our factory, can make in accordance with customer's special requirement.

1608 Series SMD Chip LED Lamps Packaging Specifications

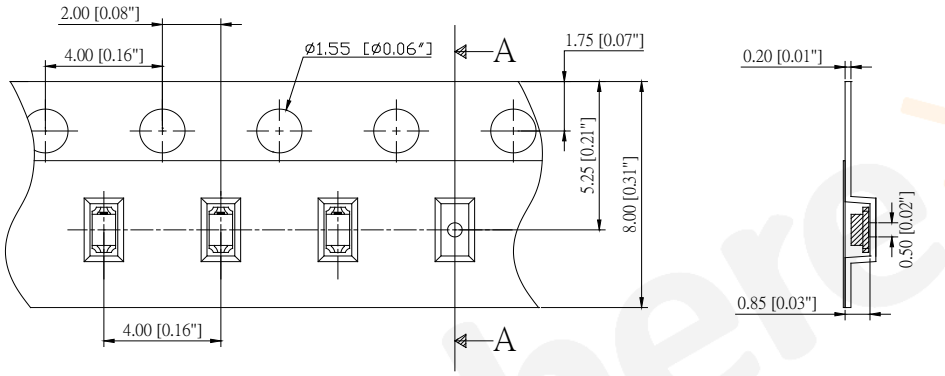
- **Feeding Direction**



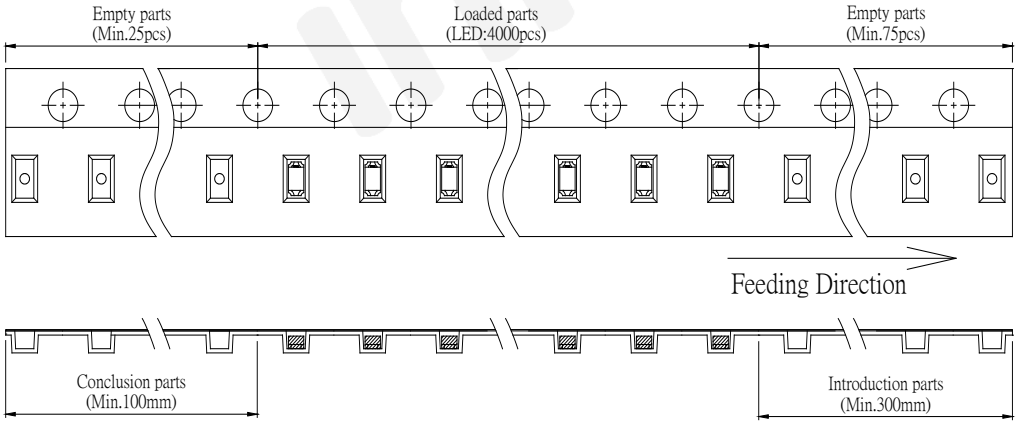
- **Dimensions of Reel (Unit: mm)**



- **Dimensions of Tape (Unit: mm)**



- **Arrangement of Tape**

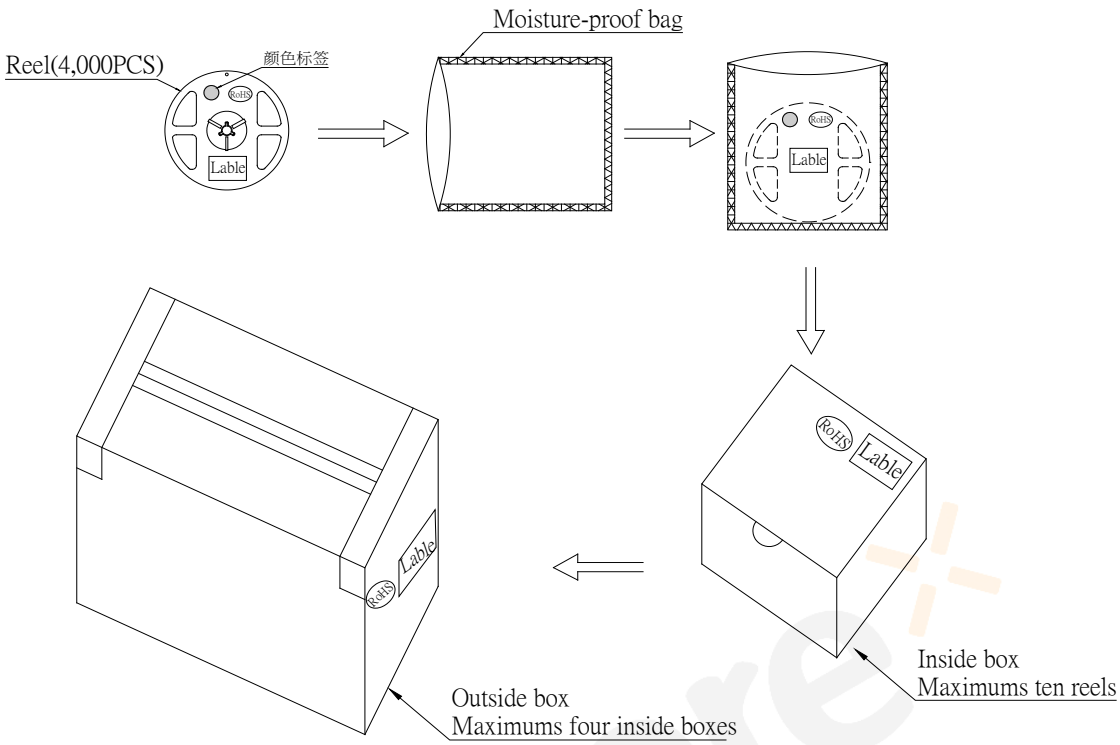


Notes:

1. Empty component pockets are sealed with top cover tape;
2. The maximum number of missing lamps is two;
3. The cathode is oriented towards the tape sprocket hole in accordance with ANSI/EIA RS-481 specifications.
4. 4,000pcs/Reel.

1608 Series SMD Chip LED Lamps Packaging Specifications

- **Packaging specifications**



Notes:

Reeled products (numbers of products are 4,000pcs) packed in a seal off moisture-proof bag along with a desiccant one by one, ten moisture-proof bag of maximums (total maximum number of products are 40,000pcs) packed in an inside box (about size: 240x 230x 130mm) and four inside boxes of maximums are put in the outside box (about size: 545mm x 260mm x 250mm) Together with buffer material, and it is packed. (Part No., Lot No., quantity should appear on the label on the moisture-proof bag, part No. And quantity should appear on the label on the cardboard box.) The number of the loading steps of outside box (cardboard box) has it to three steps.